

## C1206C561JFGACTU

Aliases (C1206C561JFGAC7800) SMD Comm COG HV, Ceramic, 560 pF, 5%, 1,500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1206, 1.5 mm



Click here for the 3D model.

1206

3.2mm +/-0.2mm

1.6mm +/-0.2mm

1.6mm +/-0.15mm

0.5mm +/-0.25mm

T&R, 180mm, Plastic Tape

1.5mm MIN

2000

| General Information      |   |
|--------------------------|---|
| Series                   | SMD Comm COG HV                               |
| Style                    | SMD Chip                                      |
| Description              | SMD, MLCC, Ultra-Stable, Low<br>Loss, Class I |
| Features                 | Ultra-Stable, Low Loss, Class I               |
| RoHS                     | Yes   |
| Termination              | Tin   |
| Marking                  | No  |
| AEC-Q200                 | No  |
| Typical Component Weight | 36 mg   |
| Shelf Life               | 78 Weeks                                      |
| MSL                      | 1   |

| Specifications   |                           |
|--|---------------------------|
| Capacitance  | 560 pF                    |
| Measurement Condition  | 1 MHz 1.0Vrms             |
| Tolerance  | 5%                        |
| Voltage DC   | 1500 VDC                  |
| Dielectric Withstanding Voltage  | 1,800 VDC                 |
| Temperature Range  | -55/+125°C                |
| Temp. Coefficient  | COG                       |
| Capacitance Change with<br>Reference to +25°C and 0 VDC<br>Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1 MHz 1.0Vrms        |
| Aging Rate   | 0% Loss/Decade Hour       |
| Insulation Resistance  | 100 GOhms                 |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions

**Packaging Specifications** 

Packaging Quantity

Chip Size

L

W T

s

В

Packaging